

CLAIMS

1. A transport and storage carrier for semiconductor members including wafers which is characterized in that the carrier is molded from a resin composition comprising a synthetic resin having a melting temperature of at least 300°C and a carbon fibril admixed with the resin, the molded carrier being 1 to 5 seconds in average charge decay time for decay of 1,000 V to 5 V.

2. A carrier according to claim 1 wherein the synthetic resin is polyetheretherketone, polyetherimide or polyethersulfone.

3. A carrier according to claim 1 wherein the carbon fibril is 3.5 to 75 nm in average diameter and 5 to 1000 in aspect ratio.

4. A carrier according to claim 1 wherein 1 to 10 parts by weight of the carbon fibril is used per 100 parts by weight of the synthetic resin.